



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20170609003
Datasheet Reflow Information Update
Information Only**

Date: June 14, 2017
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMZ31710RVQR	null
LMZ31710RVQT	null
LMZ35003RKGT	null
TPS84320RUQR	null
TPS84320RUQT	null
LMZ30606RKGR	null
LMZ30606RKGT	null
LMZ31520RLGT	null
LMZ31707RVQR	null
LMZ34002RKGT	null
LMZ30602RKGT	null
LMZ31503RUQR	null
LMZ31530RLGT	null
LMZ34002RKGR	null
LMZ35003RKGR	null
TPS84610RKGR	null
LMZ30604RKGT	null
LMZ31707RVQT	null
LMZ31503RUQT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170609003	PCN Date:	June 14, 2017
Title:	Datasheet Reflow Information Update		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
☐	Assembly Site	☐	Design
☐	Assembly Process	☒	Data Sheet
☐	Assembly Materials	☐	Part number change
☐	Mechanical Specification	☐	Test Site
☐	Packing/Shipping/Labeling	☐	Test Process
		☐	Wafer Bump Site
		☐	Wafer Bump Material
		☐	Wafer Bump Process
		☐	Wafer Fab Site
		☐	Wafer Fab Materials
		☐	Wafer Fab Process

Notification Details		
Description of Change:		
Texas Instruments Incorporated is announcing an information only notification.		
The product datasheets are being updated as summarized below. See the change description below.		
Change Description:		
Revision History:		
-Added peak reflow and maximum number of reflows information		
ABSOLUTE MAXIMUM RATINGS table update		
Peak Reflow Case Temperature ⁽³⁾	240 °C	
Maximum Number of Reflows Allowed ⁽³⁾	1	
The datasheet revision numbers will be changing.		
Device Family	Change From:	Change To:
LMZ31506	SNVS993	SNVS993A
LMZ31530	SLVSBC7B	SLVSBC7C
LMZ31704	SLVSBV8A	SLVSBV8B
LMZ31707	SLVSBV7A	SLVSBV7B
LMZ31710	SNVS987A	SNVS987B
LMZ34002	SNVS989A	SNVS989B
LMZ34202	SNVSAJ2	SNVSAJ2A
LMZ35003	SNVS988	SNVS988A
LMZ36002	SNVSA92A	SNVSA92B
TPS84210	SLUSAN7A	SLUSAN7B
TPS84250	SLVSAR6A	SLVSAR6B
TPS84259	SLVSBA0B	SLVSBA0C
TPS84320	SLUSAH7	SLUSAH7A
TPS84410	SLVSAR5A	SLVSAR5B
TPS84610	SLVSAZ4	SLVSAZ4A
TPS84620	SLVSA43D	SLVSA43E
TPS84621	SLVSAW7C	SLVSAW7D
TPS84A20	SLVSBC6	SLVSBC6A
LMZ30604	SNVS998	SNVS998A
LMZ31503	SNVS992	SNVS992A
LMZ31506H	SNVS996	SNVS996A
LMZ30602	SNVS997	SNVS997A
LMZ30606	SNVS995	SNVS995A

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMZ31506>
<http://www.ti.com/product/LMZ31530>
<http://www.ti.com/product/LMZ31704>
<http://www.ti.com/product/LMZ31707>
<http://www.ti.com/product/LMZ31710>
<http://www.ti.com/product/LMZ34002>
<http://www.ti.com/product/LMZ34202>
<http://www.ti.com/product/LMZ35003>
<http://www.ti.com/product/LMZ36002>
<http://www.ti.com/product/TPS84210>
<http://www.ti.com/product/TPS84250>
<http://www.ti.com/product/TPS84259>
<http://www.ti.com/product/TPS84320>
<http://www.ti.com/product/TPS84410>
<http://www.ti.com/product/TPS84610>
<http://www.ti.com/product/TPS84620>
<http://www.ti.com/product/TPS84621>
<http://www.ti.com/product/TPS84A20>
<http://www.ti.com/product/LMZ30604>
<http://www.ti.com/product/LMZ31503>
<http://www.ti.com/product/LMZ30602>
<http://www.ti.com/product/LMZ30606>
<http://www.ti.com/product/LMZ31506H>

Reason for Change:

To accurately represent the device characteristics. A potential issue has been identified through ongoing reliability monitor (ORM) testing showing solder extrusion on some devices after reflow at 260C peak temperature. This is primarily a visual anomaly since all ORM testing has passed pre/post electrical testing from moisture sensitivity level three (3) (MSL3) at 260C peak reflow temperature and 500 cycles temperature cycling (T/C) using -65/+150C.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

The reflow temperature change is reflected on the label.

Sample product shipping label (not actual product label)



Product Affected:			
LMZ31506RUQR	LMZ31506RUQT	LMZ31530RLGT	LMZ31704RVQR
LMZ31704RVQT	LMZ31707RVQR	LMZ31707RVQT	LMZ31710RVQR
LMZ31710RVQT	LMZ34002RKGR	LMZ34002RKGT	LMZ34202RVQR
LMZ34202RVQT	LMZ35003RKGR	LMZ35003RKGT	LMZ36002RVQR
LMZ36002RVQT	TPS84210RKGR	TPS84210RKGT	TPS84250RKGR
TPS84250RKGT	TPS84259RKGR	TPS84259RKGT	TPS84320RUQR
TPS84320RUQT	TPS84410RKGR	TPS84410RKGT	TPS84610RKGR
TPS84610RKGT	TPS84620RUQR	TPS84620RUQT	TPS84621RUQR
TPS84621RUQT	TPS84A20RVQR	TPS84A20RVQT	LMZ30604RKGR
LMZ30604RKGT	LMZ31503RUQR	LMZ31503RUQT	LMZ30602RKGR
LMZ30602RKGT	LMZ30606RKGR	LMZ30606RKGT	LMZ31506HRUQR
LMZ31506HRUQT	LMZ31520RLGT	LMZ31503RUQR-P	LMZ31506RUQR-P
LMZ35003RKGR-P			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com